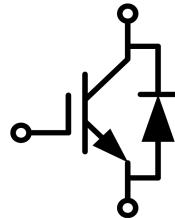


## IGBT Discrete with Anti-Parallel Diode

### 电气特性/ Features And Benefits:

- 650V 沟槽栅/场终止工艺  
650V trench gate/field termination process
- 低开关损耗  
Low switching losses
- V<sub>CESAT</sub> 正温度系数  
V<sub>CESAT</sub> has a positive temperature coefficient



### 典型应用/Applications:

- 充电桩  
Charging station
- OBC  
On board charger
- 不间断电源  
Uninterruptible power supplies
- 逆变器  
Inverters



### 关键性能和程序参数 / Key Performance And Package Parameters

Type	V <sub>CE</sub>	I <sub>C</sub>	V <sub>CESAT</sub> , T <sub>vj</sub> =25°C	T <sub>vjmax</sub>	Package
SD50R07A6	650V	50A	1.58V	175°C	TO-247-3L

## 双极晶体管/IGBT

### 最大额定值 / Maximum Ratings

Parameter	Conditions	Symbol	Value	Unit
集电极-发射极电压 Collector-Emitter Voltage	T <sub>vj</sub> =25°C	V <sub>CES</sub>	650	V
连续集电极直流电流 Continuous DC collector current	T <sub>c</sub> =25°C, T <sub>vj max</sub> =175°C T <sub>c</sub> =100°C, T <sub>vj max</sub> =175°C	I <sub>C</sub>	80 50	A

集电极脉冲电流 Pulsed collector current, tp limited by $T_{vj\ max}$		$I_{Cpuls}$	200	A
总功率损耗 Total power dissipation	$T_C = 25^\circ C, T_{vj\ max} = 175^\circ C$ $T_C = 100^\circ C, T_{vj\ max} = 175^\circ C$	$P_{tot}$	295 150	W
栅极-发射极电压 Gate emitter Voltage	$t_p \leq 10\ \mu s, D < 0.010$	$V_{GE}$	$\pm 20$ $\pm 30$	V
在开关状态下温度 Temperature under switching conditions		$T_{vj\ op}$	-40...+175	°C
储存温度 Storage temperature		$T_{stg}$	-40...+150	°C

## 热特性 / Thermal Characteristics

Parameter	Conditions	Symbol	Value			Unit
			Min.	Typ.	Max.	
热阻, 结-环境 Thermal resistance, junction-ambient		$R_{th(j-a)}$			40	K/W
IGBT 热阻, 结-壳 IGBT thermal resistance, junction - case		$R_{th(j-C)}$		0.51		K/W
二极管热阻, 结-壳 Diode thermal resistance, junction - case		$R_{th(j-C)}$		0.43		K/W

## 特征值 / Characteristic Values

Parameter	Conditions	Symbol	Value			Unit
			Min.	Typ.	Max.	
击穿电压 Collector-emitter breakdown voltage	$V_{GE}=0V, I_C=0.25mA$	$V_{(BR)CES}$	650			
集电极-发射极饱和电压 Collector-Emitter saturationVoltage	$V_{GE}=15V, I_C=50A$ $V_{GE}=15V, I_C=50A$ $V_{GE}=15V, I_C=50A$	$T_{vj}=25^\circ C$ $T_{vj}=125^\circ C$ $T_{vj}=150^\circ C$		1.58 1.87 1.95	2.10	V
栅极-发射极阈值电压 Gate-Emitter thresholdVoltage	$I_C=0.5mA, V_{GE}=V_{CE}$	$T_{vj}=25^\circ C$	$V_{GE(th)}$	4.2	5.0	5.8
跨导 Transconductance	$V_{CE}=20V, I_C=50A$	$G_{fs}$		77		S
输入电容 Input capacitance	$f=100kHz, V_{CE}=25V, V_{GE}=0V$	$T_{vj}=25^\circ C$	$C_{ies}$		5.46	
输出电容 Output capacitance			$C_{oes}$		0.20	nF
反向传输电容 Reverse transfer capacitance			$C_{res}$		0.10	
门极电荷 Gate charge	$I_C=50A, V_{GE}=15V, V_{CE}=520V$	$T_{vj}=25^\circ C$	$Q_G$		0.53	$\mu C$

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集电极-发射极截止电流 Collector-emitter cut-off current	$V_{CE}=650V, V_{GE}=0V$	$T_{vj}=25^{\circ}C$ $T_{vj}=175^{\circ}C$	$I_{CES}$		2000	50	uA
栅极-发射极漏电流 Gate-emitter leakage current	$V_{CE}=0V, V_{GE}=20V$	$T_{vj}=25^{\circ}C$	$I_{GES}$			100	nA
开通延迟时间 Turn-on delay time	$I_c=50A, V_{CE}=400V$ $V_{GE}=\pm 15V, R_G=8\Omega$ (电感负载) / (inductive load)	$T_{vj}=25^{\circ}C$ $T_{vj}=125^{\circ}C$ $T_{vj}=150^{\circ}C$	$t_{d\ on}$		33 21 19		
上升时间 Rise time	$I_c=50A, V_{CE}=400V$ $V_{GE}=\pm 15V, R_G=8\Omega$ (电感负载) / (inductive load)	$T_{vj}=25^{\circ}C$ $T_{vj}=125^{\circ}C$ $T_{vj}=150^{\circ}C$	$t_r$		75 67 65		
关断延迟时间 Turn-off delay time	$I_c=50A, V_{CE}=400V$ $V_{GE}=\pm 15V, R_G=8\Omega$ (电感负载) / (inductive load)	$T_{vj}=25^{\circ}C$ $T_{vj}=125^{\circ}C$ $T_{vj}=150^{\circ}C$	$t_{d\ off}$		21 32 38		ns
下降时间 Fall time	$I_c=50A, V_{CE}=400V$ $V_{GE}=\pm 15V, R_G=8\Omega$ (电感负载) / (inductive load)	$T_{vj}=25^{\circ}C$ $T_{vj}=125^{\circ}C$ $T_{vj}=150^{\circ}C$	$t_f$		41 62 62		
开通损耗能量 (每脉冲) Turn-on energy loss per pulse	$I_c=50A, V_{CE}=400V$ $V_{GE}=\pm 15V, R_G=8\Omega$ (电感负载) / (inductive load)	$T_{vj}=25^{\circ}C$ $T_{vj}=125^{\circ}C$ $T_{vj}=150^{\circ}C$	$E_{on}$		2.37 2.88 3.10		
关断损耗能量 (每脉冲) Turn-off energy loss per pulse	$I_c=50A, V_{CE}=400V$ $V_{GE}=\pm 15V, R_G=8\Omega$ (电感负载) / (inductive load)	$T_{vj}=25^{\circ}C$ $T_{vj}=125^{\circ}C$ $T_{vj}=150^{\circ}C$	$E_{off}$		0.60 0.73 0.76		mJ
开关损耗能量 (每脉冲) Total switching energy	$I_c=50A, V_{CE}=400V$ $V_{GE}=\pm 15V, R_G=8\Omega$ (电感负载) / (inductive load)	$T_{vj}=25^{\circ}C$ $T_{vj}=125^{\circ}C$ $T_{vj}=150^{\circ}C$	$E_{ts}$		2.97 3.61 3.86		

## 二极管/Diode

### 最大额定值 / Maximum Ratings

Parameter	Conditions	Symbol	Value		Unit
反向重复峰值电压 Repetitive peak reverse Voltage	$T_{vj}=25^{\circ}C$	$V_{RRM}$	650		V
连续正向直流电流 Continuous DC forward current	$T_C=25^{\circ}C, T_{vj\ max}=175^{\circ}C$ $T_C=100^{\circ}C, T_{vj\ max}=175^{\circ}C$	$I_F$	100 50		A
二极管脉冲电流 Diode pulsed current, tp limited by $T_{vj\ max}$		$I_{Fpuls}$	150		A

### 特征值 / Characteristic Values

Parameter	Conditions	Symbol	Value			Unit
			Min.	Typ.	Max.	
正向电压 Forward Voltage	$I_F=50A, V_{GE}=0V$ $I_F=50A, V_{GE}=0V$ $I_F=50A, V_{GE}=0V$	$V_F$		1.63 1.42 1.37	2.1	V

反向恢复峰值电流 Peak reverse recovery current	$I_F=50A$ , $-di_F/dt=400A/\mu s$ ( $T_{vj}=150^\circ C$ ) $V_R=400V, V_{GE}=-15V$	$T_{vj}=25^\circ C$ $T_{vj}=125^\circ C$ $T_{vj}=150^\circ C$	$I_{RM}$		21 29 32		A
反向恢复电荷 Reverse Recovered charge	$I_F=50A$ , $-di_F/dt=400A/\mu s$ ( $T_{vj}=150^\circ C$ ) $V_R=400V, V_{GE}=-15V$	$T_{vj}=25^\circ C$ $T_{vj}=125^\circ C$ $T_{vj}=150^\circ C$	$Q_{rr}$		1.48 3.26 3.95		$\mu C$
反向恢复时间 Reverse Recovery Time	$I_F=50A$ , $-di_F/dt=400A/\mu s$ ( $T_{vj}=150^\circ C$ ) $V_R=400V, V_{GE}=-15V$	$T_{vj}=25^\circ C$ $T_{vj}=125^\circ C$ $T_{vj}=150^\circ C$	$t_{rr}$		133 199 218		ns
反向恢复损耗 (每脉冲) Reverse recovered energy	$I_F=50A$ , $-di_F/dt=400A/\mu s$ ( $T_{vj}=150^\circ C$ ) $V_R=400V, V_{GE}=-15V$	$T_{vj}=25^\circ C$ $T_{vj}=125^\circ C$ $T_{vj}=150^\circ C$	$E_{rec}$		0.34 0.66 0.78		mJ

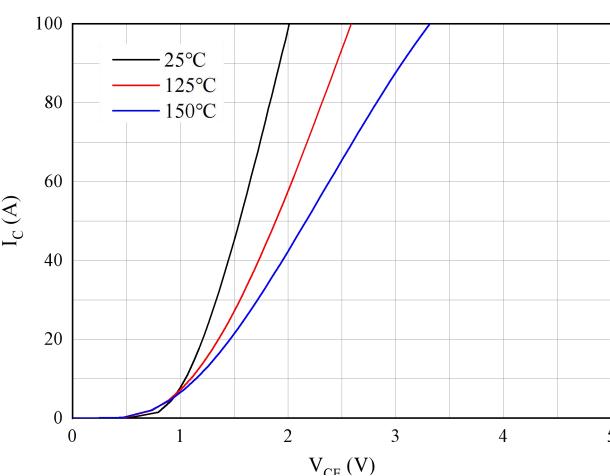
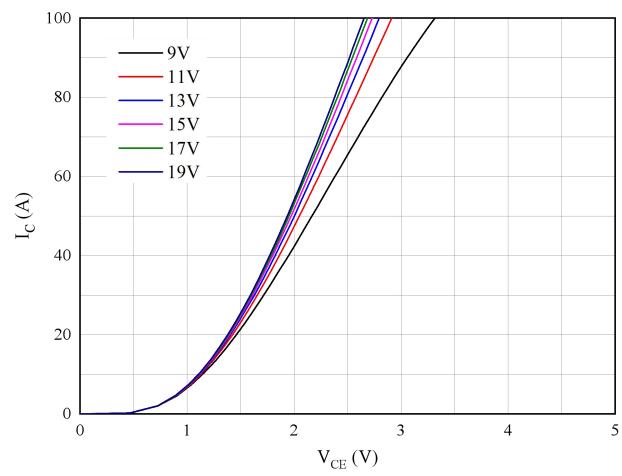
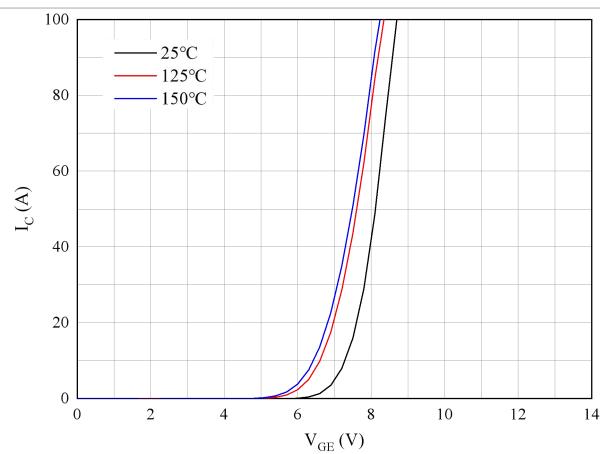
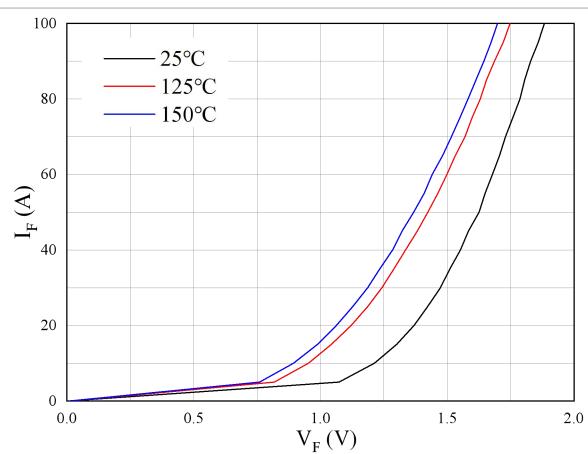
图 1. 典型输出特性 ( $V_{GE}=15V$ )Figure 1. Typical output characteristics ( $V_{GE}=15V$ )图 2. 典型输出特性 ( $T_{vj}=150^{\circ}C$ )Figure 2. Typical output characteristics ( $T_{vj}=150^{\circ}C$ )图 3. 典型传输特性( $V_{CE}=20V$ )Figure 3. Typical transfer characteristic( $V_{CE}=20V$ )

图 4. 正向偏压特性 二极管

Figure 4. Forward characteristic of Diode

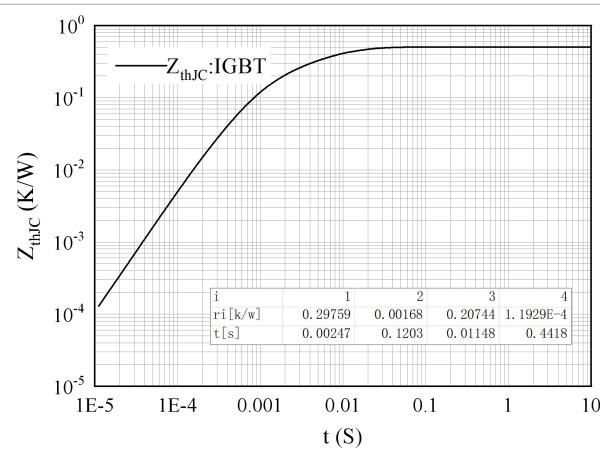


图 5. 瞬态热阻抗 IGBT

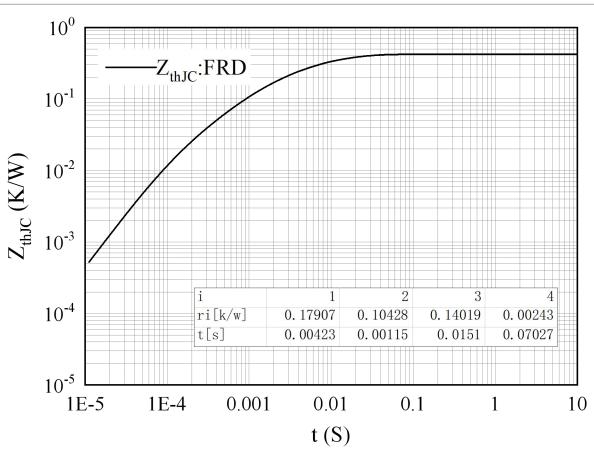
Figure 5. Transient thermal impedance IGBT,  
 $Z_{thJC}=f(t)$ 

图 6. 瞬态热阻抗 FRD

Figure 6. Transient thermal impedance FRD,  
 $Z_{thJC}=f(t)$

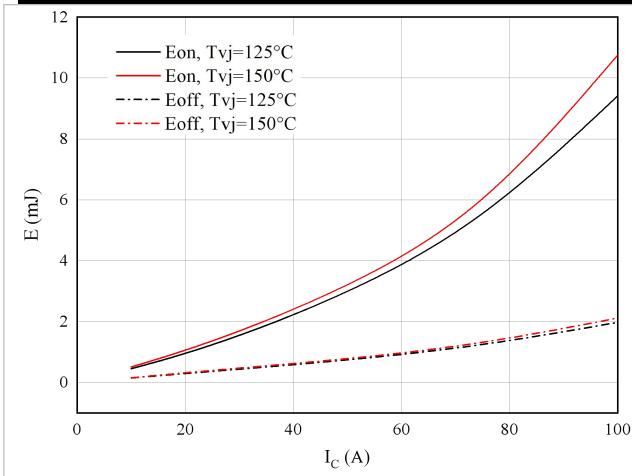


图 7. 开关损耗

Figure 7. Switching losses of IGBT

VGE=±15V, RGon=8Ω, RGoff=8Ω, VCE=400V

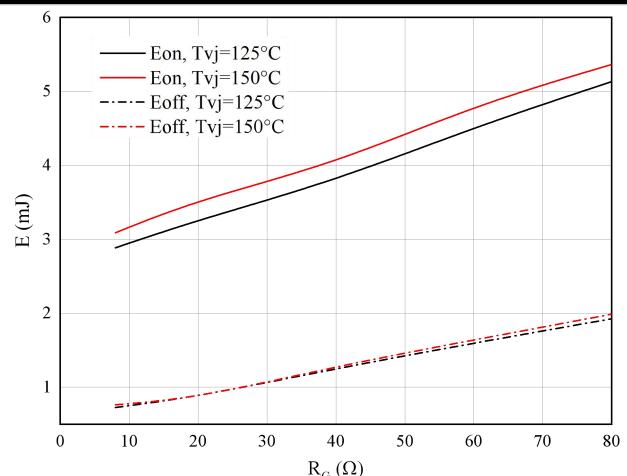


图 8. 开关损耗

Figure 8. Switching losses of IGBT

VGE=±15V, IC=50A, VCE=400V

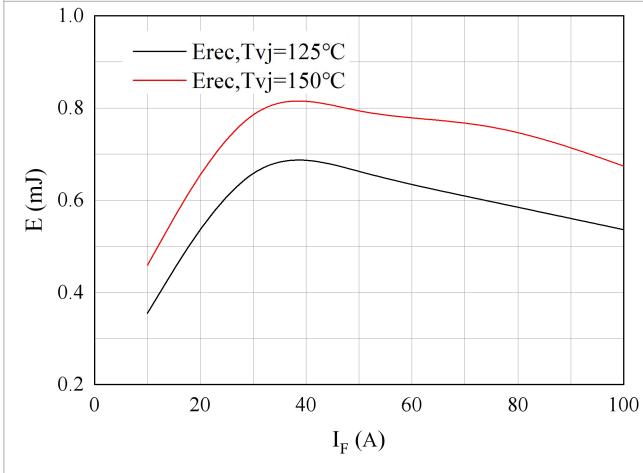


图 9. 开关损耗 二极管

Figure 9. Switching losses of Diode

Rgon=8Ω, VCE=400V

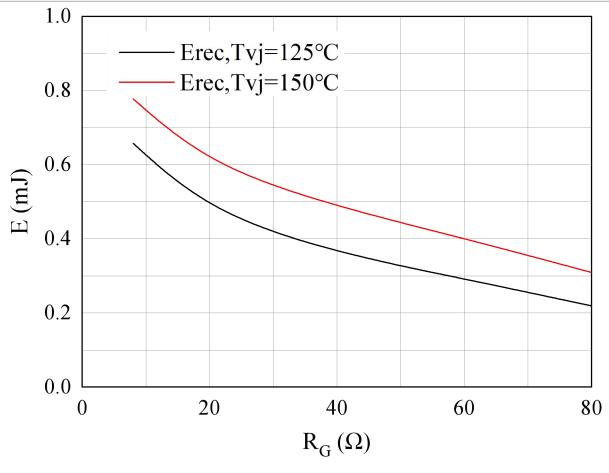


图 10. 开关损耗 二极管

Figure 10. Switching losses of Diode

IF=50A, VCE=400V

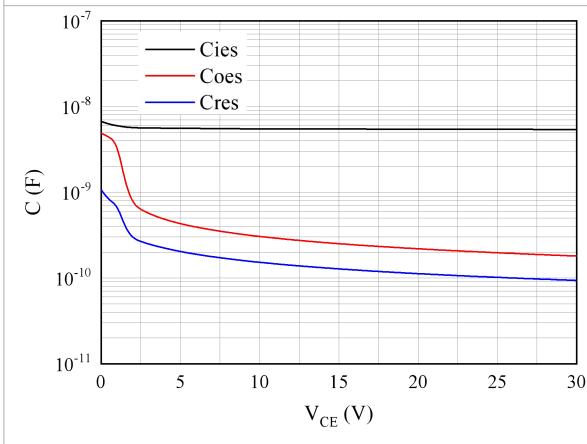
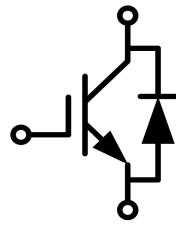


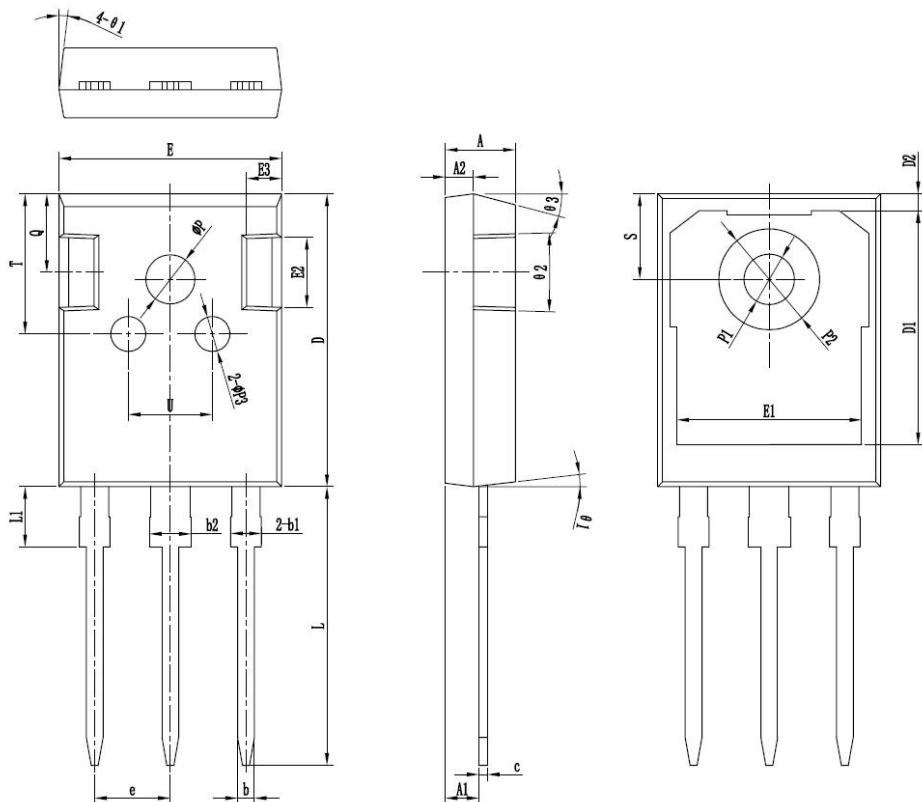
图 11. 电容特性

Figure 11. Capacitance characteristic

## 接线图 / Circuit diagram



## 封装尺寸 / Package outlines



符号	单位:mm		
	MIN	NOM	MAX
a <sub>1</sub>	4.90	5.00	5.10
*a <sub>1</sub>	2.31	2.41	2.51
A <sub>2</sub>	1.90	2.00	2.10
b <sub>1</sub>	1.15	1.20	1.25
*b <sub>1</sub>	1.95	2.10	2.25
b <sub>2</sub>	2.95	3.10	3.25
c <sub>1</sub>	0.55	0.60	0.65
e <sub>1</sub>	20.90	21.00	21.10
D <sub>1</sub>	16.35	16.55	16.75
D <sub>2</sub>	1.05	1.20	1.35
*E	15.70	15.80	15.90
E <sub>1</sub>	13.10	13.25	13.40
E <sub>2</sub>	4.90	5.00	5.10
E <sub>3</sub>	2.40	2.50	2.60
q <sub>1</sub>	5.40	5.44	5.48
s <sub>1</sub>	19.80	19.92	20.10
*s <sub>1</sub>	-	-	4.30
*d <sub>1</sub>	3.70	3.80	3.90
*d <sub>1</sub>	3.50	3.60	3.70
d <sub>2</sub>	7.00	7.20	7.40
d <sub>3</sub>	2.40	2.50	2.60
Q	5.60	5.80	6.00
*S	6.05	6.15	6.25
T	9.80	10.00	10.20
U	6.00	6.20	6.40
G <sub>1</sub>	5°	7°	9°
G <sub>2</sub>	1°	3°	5°
G <sub>3</sub>	13°	15°	17°

\*为关键管控尺寸